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- (54) **Title:** ELECTROPLATING WITH TEMPORARY FEATURES

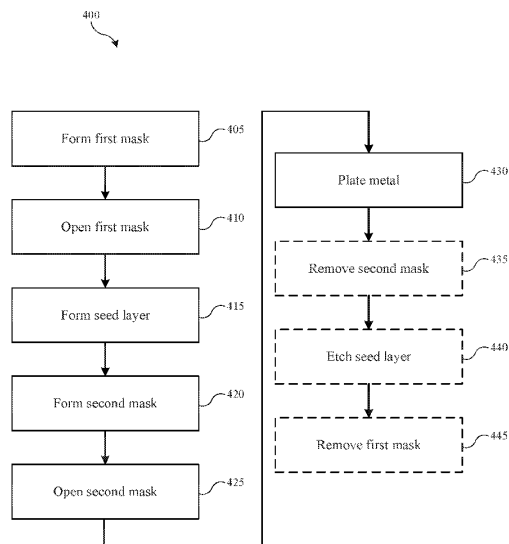


FIG. 4

- (57) **Abstract:** Exemplary methods of electroplating may include forming a first mask layer on a semiconductor substrate. The methods may include forming a seed layer overlying the first mask layer. The methods may include forming a second mask layer overlying the seed layer. The methods may include plating an amount of metal on the semiconductor substrate. A portion of the metal may plate over the first mask layer.

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